# ABSTRACT

**APPARATUS FOR APPLYING A SINTERING FORCE VIA A COMPRESSIBLE FILM**

A sintering apparatus for simultaneously sintering an electronic device onto a substrate, and a metallic sheet onto the electronic device includes a sinter tool and a compressible film positionable onto the metallic sheet and the electronic device. A thickness of the compressible film is greater than a height of the metallic sheet. The compressible film is adapted to conform to a shape of the metallic sheet and the electronic device to simultaneously cover the metallic sheet and at least a part of the electronic device when the sinter tool applies a sintering force onto the compressible film during a sintering process.

(FIG. 4D)